

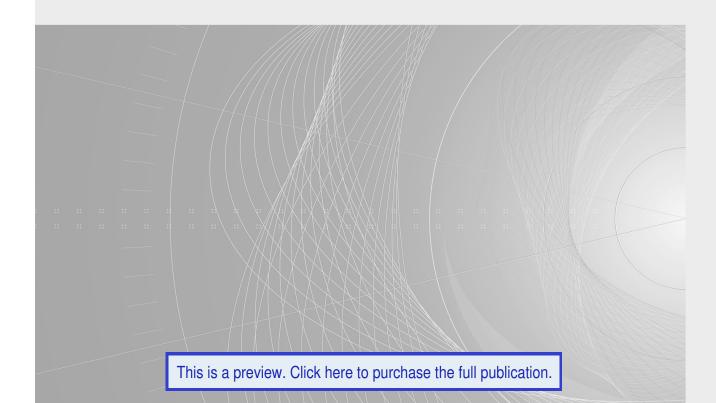
Edition 4.1 2017-07

# CONSOLIDATED VERSION



**Environmental testing -**

Part 2-58: Tests – Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)





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INTERNATIONAL ELECTROTECHNICAL COMMISSION

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#### INTERNATIONAL ELECTROTECHNICAL COMMISSION

#### **ENVIRONMENTAL TESTING -**

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